

**Features**

- ★ Advanced Trench MOS Technology
- ★ 100% EAS Guaranteed
- ★ Reliable and Rugged
- ★ Green Device Available

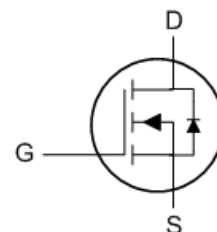
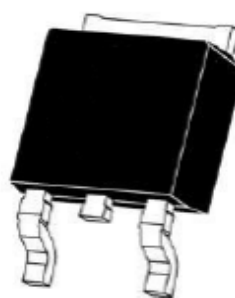
**Product Summary**

| BVDSS | RDSON | ID  |
|-------|-------|-----|
| 100V  | 26mΩ  | 30A |

**Applications**

- ★ Synchronous Rectification in SMPS.
- ★ Hard Switching and High Speed Circuit.
- ★ DC/DC in Telecoms and Industrial.

**TO252 Pin Configuration**



**Absolute Maximum Ratings**

| Symbol                                | Parameter                                  | Rating     | Units |
|---------------------------------------|--|------------|-------|
| V <sub>DS</sub>                       | Drain-Source Voltage                       | 100        | V     |
| V <sub>GS</sub>                       | Gate-Source Voltage                        | ±20        | V     |
| I <sub>D</sub> @T <sub>C</sub> =25°C  | Continuous Drain Current <sup>1</sup>      | 30         | A     |
| I <sub>D</sub> @T <sub>C</sub> =100°C | Continuous Drain Current <sup>1</sup>      | 18.5       | A     |
| I <sub>DM</sub>                       | Pulsed Drain Current <sup>2</sup>          | 120        | A     |
| EAS                                   | Single Pulse Avalanche Energy <sup>3</sup> | 64.8       | mJ    |
| I <sub>AS</sub>                       | Avalanche Current                          | 36         | A     |
| P <sub>D</sub> @T <sub>C</sub> =25°C  | Total Power Dissipation <sup>4</sup>       | 52         | W     |
| T <sub>STG</sub>                      | Storage Temperature Range                  | -55 to 150 | °C    |
| T <sub>J</sub>                        | Operating Junction Temperature Range       | -55 to 150 | °C    |

**Thermal Data**

| Symbol           | Parameter  | Typ. | Max. | Unit |
|------------------|--|------|------|------|
| R <sub>θJA</sub> | Thermal Resistance Junction-ambient <sup>1</sup> | ---  | 50   | °C/W |
| R <sub>θJC</sub> | Thermal Resistance Junction-case <sup>1</sup>    | ---  | 2.4  | °C/W |

**Electrical Characteristics (T<sub>J</sub>=25 °C, unless otherwise noted)**

| Symbol              | Parameter                                      | Conditions  | Min. | Typ. | Max. | Unit |
|---------------------|--|---|------|------|------|------|
| BV <sub>DSS</sub>   | Drain-Source Breakdown Voltage                 | V <sub>GS</sub> =0V , I <sub>D</sub> =250uA   | 100  | ---  | ---  | V    |
| R <sub>DS(ON)</sub> | Static Drain-Source On-Resistance <sup>2</sup> | V <sub>GS</sub> =10V , I <sub>D</sub> =8A   | ---  | 22   | 26   | mΩ   |
|                     |  | V <sub>GS</sub> =4.5V , I <sub>D</sub> =4A  | ---  | 24   | 32   | mΩ   |
| V <sub>GS(th)</sub> | Gate Threshold Voltage                         | V <sub>GS</sub> =V <sub>DS</sub> , I <sub>D</sub> =250uA                                  | 1.2  | 1.8  | 2.5  | V    |
| I <sub>DSS</sub>    | Drain-Source Leakage Current                   | V <sub>DS</sub> =80V , V <sub>GS</sub> =0V , T <sub>J</sub> =25°C                         | ---  | ---  | 1    | uA   |
|                     |  | V <sub>DS</sub> =80V , V <sub>GS</sub> =0V , T <sub>J</sub> =55°C                         | ---  | ---  | 5    |      |
| I <sub>GSS</sub>    | Gate-Source Leakage Current                    | V <sub>GS</sub> =±20V , V <sub>DS</sub> =0V   | ---  | ---  | ±100 | nA   |
| Q <sub>g</sub>      | Total Gate Charge (10V)                        | V <sub>DS</sub> =30V , V <sub>GS</sub> =10V , I <sub>D</sub> =8A                          | ---  | 57   | ---  | nC   |
| Q <sub>gs</sub>     | Gate-Source Charge                             |   | ---  | 8.7  | ---  |      |
| Q <sub>gd</sub>     | Gate-Drain Charge                              |   | ---  | 14   | ---  |      |
| T <sub>d(on)</sub>  | Turn-On Delay Time                             | V <sub>DD</sub> =30V , V <sub>GS</sub> =10V , R <sub>G</sub> =3.3Ω,<br>I <sub>D</sub> =1A | ---  | 16.2 | ---  | ns   |
| T <sub>r</sub>      | Rise Time                                      |   | ---  | 41.2 | ---  |      |
| T <sub>d(off)</sub> | Turn-Off Delay Time                            |   | ---  | 56.4 | ---  |      |
| T <sub>f</sub>      | Fall Time                                      |   | ---  | 16.2 | ---  |      |
| C <sub>iss</sub>    | Input Capacitance                              | V <sub>DS</sub> =25V , V <sub>GS</sub> =0V , f=1MHz                                       | ---  | 3307 | ---  | pF   |
| C <sub>oss</sub>    | Output Capacitance                             |   | ---  | 201  | ---  |      |
| C <sub>rss</sub>    | Reverse Transfer Capacitance                   |   | ---  | 151  | ---  |      |

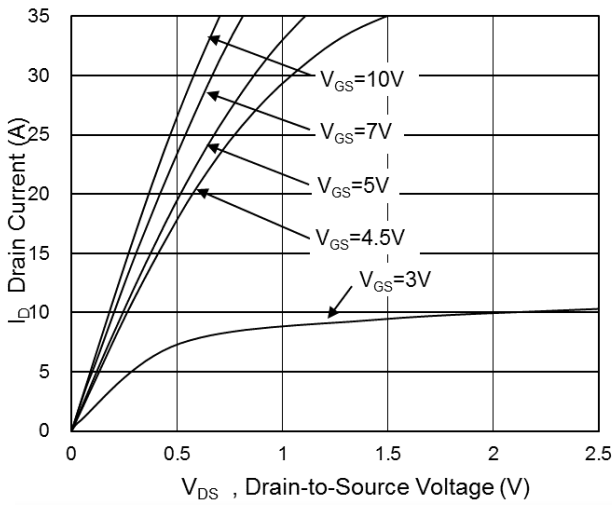
**Diode Characteristics**

| Symbol          | Parameter                                | Conditions  | Min. | Typ. | Max. | Unit |
|-----------------|--|---|------|------|------|------|
| I <sub>S</sub>  | Continuous Source Current <sup>1,5</sup> | V <sub>G</sub> =V <sub>D</sub> =0V , Force Current              | ---  | ---  | 15   | A    |
| V <sub>SD</sub> | Diode Forward Voltage <sup>2</sup>       | V <sub>GS</sub> =0V , I <sub>S</sub> =1A , T <sub>J</sub> =25°C | ---  | ---  | 1.2  | V    |
| t <sub>rr</sub> | Reverse Recovery Time                    | I <sub>F</sub> =8A , di/dt=100A/μs ,                            | ---  | 44   | ---  | nS   |
| Q <sub>rr</sub> | Reverse Recovery Charge                  | T <sub>J</sub> =25°C  | ---  | 25   | ---  |      |

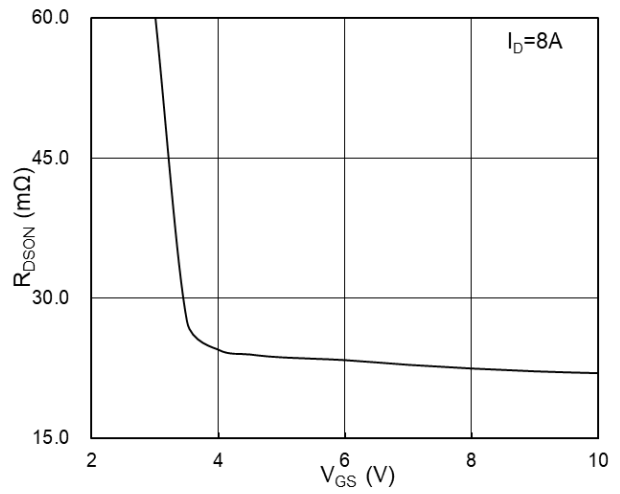
Note :

- 1.The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper.
- 2.The data tested by pulsed , pulse width ≤ 300us , duty cycle ≤ 2%
- 3.The EAS data shows Max. rating . The test condition is V<sub>DD</sub>=25V,V<sub>GS</sub>=10V,L=0.1mH,I<sub>AS</sub>=36A
- 4.The power dissipation is limited by 150°C junction temperature
- 5.The data is theoretically the same as I<sub>D</sub> and I<sub>DM</sub> , in real applications , should be limited by total power dissipation.

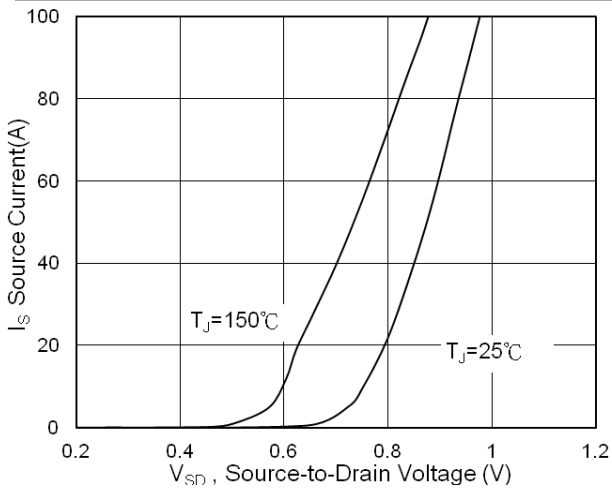
**Typical Characteristics**



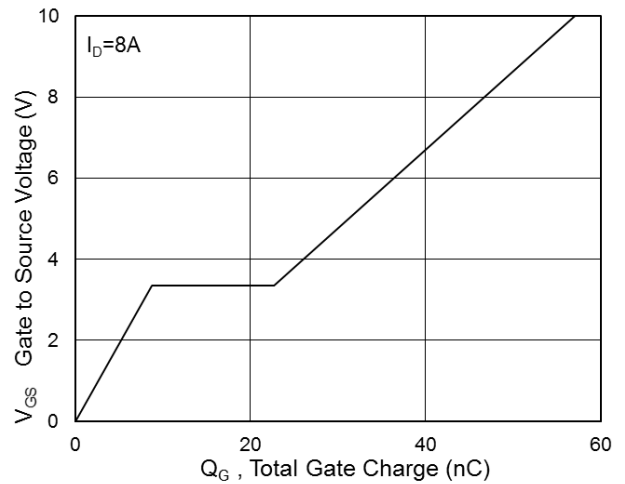
**Fig.1 Typical Output Characteristics**



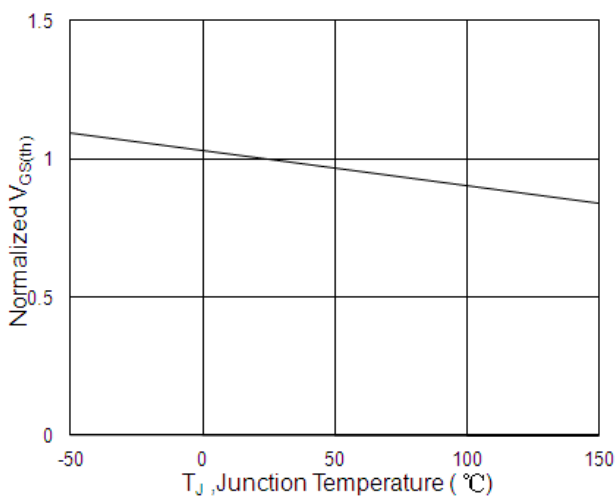
**Fig.2 On-Resistance vs G-S Voltage**



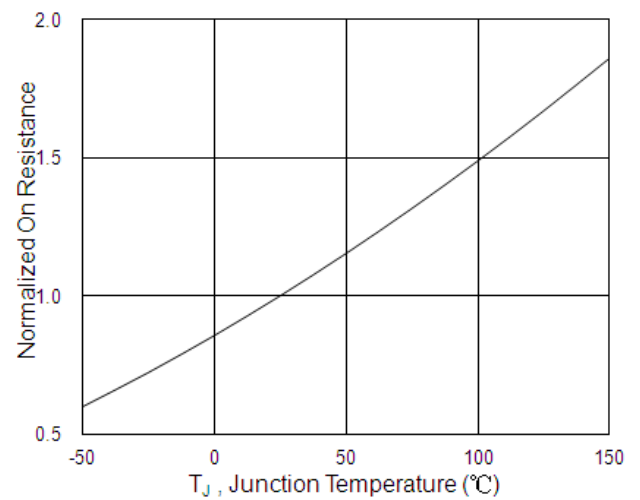
**Fig.3 Source-Drain Diode Forward Voltage**



**Fig.4 Gate-Charge Characteristics**

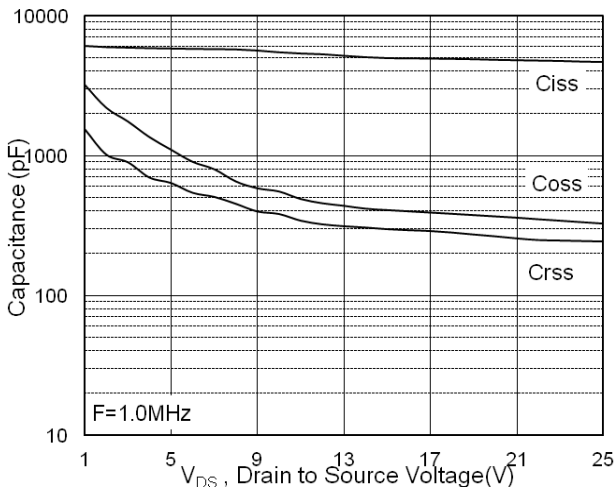


**Fig.5 Normalized  $V_{GS(th)}$  vs  $T_J$**

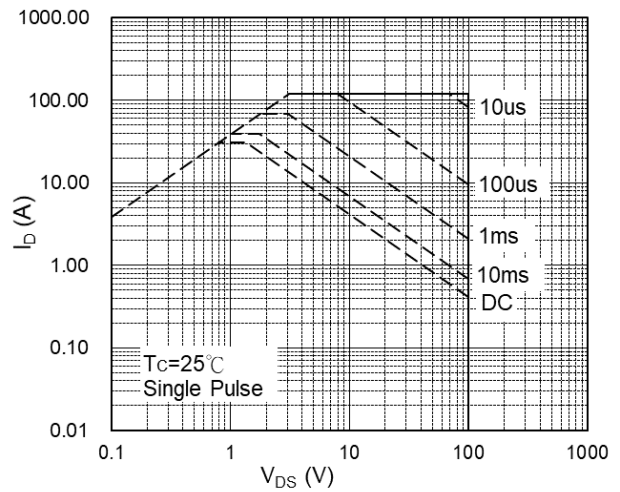


**Fig.6 Normalized  $R_{DS(on)}$  vs  $T_J$**

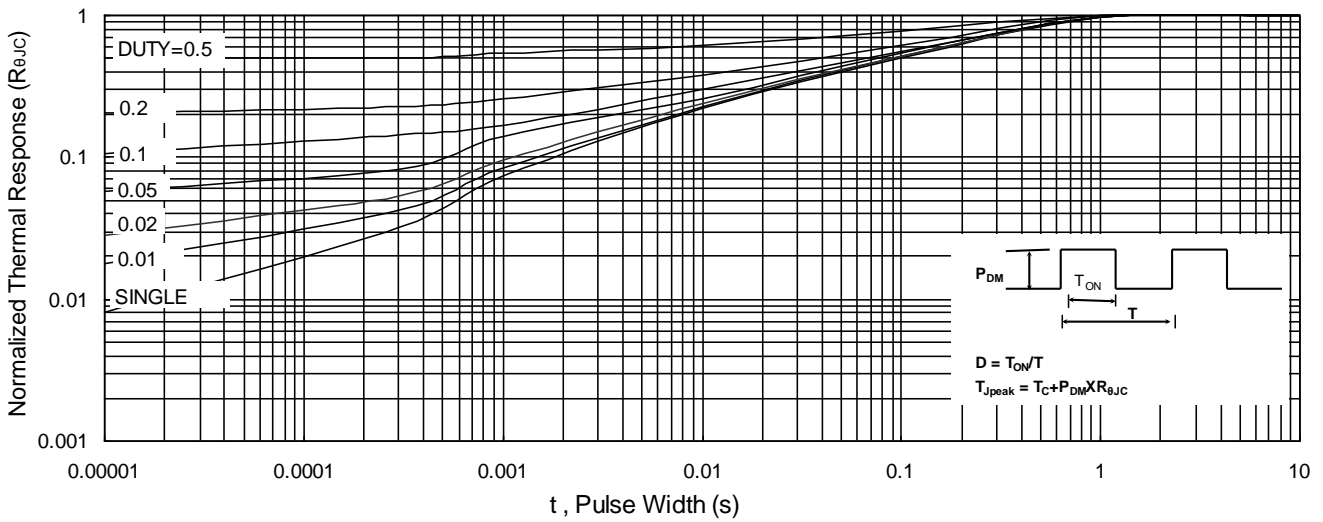
**N-Ch 100V Fast Switching MOSFETs**



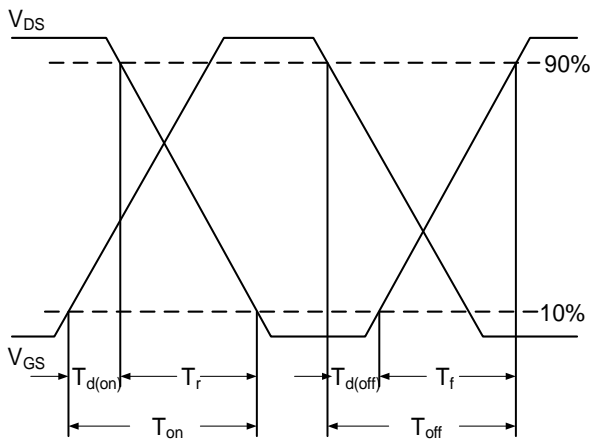
**Fig.7 Capacitance**



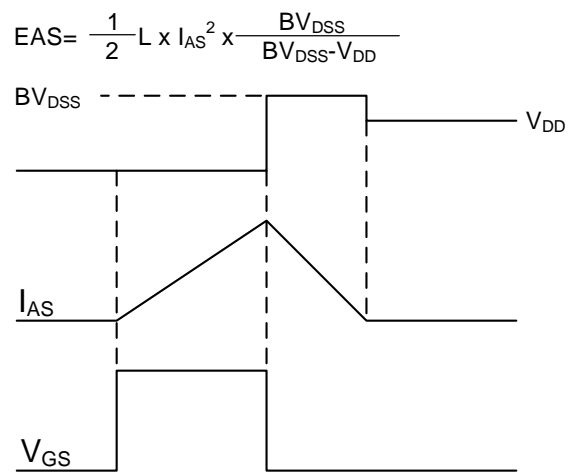
**Fig.8 Safe Operating Area**



**Fig.9 Normalized Maximum Transient Thermal Impedance**



**Fig.10 Switching Time Waveform**



**Fig.11 Unclamped Inductive Switching Waveform**